













New TPCs for T2K near detector

David Henaff on behalf of ND280 Upgrade IRN Neutrino meeting 22/06/30





Appearance channel

$$P(\nu_{\mu} \longrightarrow \nu_{e}) \approx \sin^{2} 2\theta_{13} \sin^{2} \theta_{23} \sin^{2} \frac{\Delta m_{23}^{2} L}{4E}$$
$$P(\nu_{\mu} \longrightarrow \nu_{e}) - P(\overline{\nu_{\mu}} \longrightarrow \overline{\nu_{e}}) \propto \sin \delta_{CP}$$

Disappearance channel

$$P(\nu_{\mu} \longrightarrow \nu_{\mu}) \approx 1 - \sin^2 2\theta_{23} \cos^4 \theta_{13} \sin^2 \frac{\Delta m_{23}^2 L}{4E}$$

T2K physics goals

Long baseline experiments are sensivtive to several osc. parameters

- Precise measurements of theta23 and deltam32
- Nu oscillation open questions:
 - CP symmetry
 - Octant of theta23
 - Exotic scenarios (CPT violation, sterile, ...)

ND280 current design & limitation

Goals of near detector

- Constrain neutrino flux and neutrino-nucleus interaction models
- > Clear improvements of Far detector predictions with ND

Current design

- FGDs: 2 fine grained detectors composed of plastic scintillator with layers of water
 - Act as target for nu interaction
- TPCs: 3 time projected chamber using Micromegas readout plane
 - Characterisation of outgoing particle: Momentum + PID
- POD: Upstream detector optimised to tag neutral pion detection
- All detectors are surrounded by electromagnetic calorimeter and 0.2T magnet → needed for momentum reconstruction



ND280 current design & limitation

Limitations

- Mainly a forward detector while SK is 4pi (backward track not well reconstructed)
- Hadronic part of interaction only partially reconstructed because of proton threshold and missing neutrons v_l l^-
- Loss of information → need to rely on neutrino-nucleus model to reconstruct the neutrino energy from final state lepton







ND280 upgrade

Limitations

- Mainly a forward detector while SK is 4pi (backward track not well reconstructed)
- Hadronic part of interaction only partially reconstructed because of proton threshold and missing neutrons

How to overcome this?

Remove the POD and install new sub-detectors!

- Super-FGD: Highly segmented target (~2 millions scintillator cubes readout by a 3D network WLS fibers
 - Precise location of primary vertex
 - Lower threshold for reconstruction of protons and pions + neutron measurement event by event by Time of light
- **HA-TPC:** High Angle TPC on the top and below SFGD
 - Improving angular acceptance of charged outgoing particles
- **TOF:** Whole surrounded by plastic scintillator planes to tag external background and measure track direction.



Focus on HA-TPC

Requirements

- For the new TPC:
 - > Best possible spatial separation, at least 600um as in previous TPC
 - > dE/dX resolution of 10% with 1 module (8% for 2 modules)

Field cage

- Composed of two half-TPCs with cathode in the middle (30kV)
- Field cage has thin composite walls (~39mm) to minimize multiple scattering
- Operated @ atmospheric pressure using Ar-CF4-C4H10 (95-3-2)



- ~ 400 strips
 - 200 are mirrored strip to obtain better field uniformity
- 30kV on the cathode shared by two half-TPCs





Focus on HA-TPC

Requirements

- For the new TPC:
 - Best possible spatial separation, at least 600um as in previous TPC

0.0010

0.0008

0.0006

0.0004

0.0002

0.0000 -0.0002

0

1000

2000

dE/dX resolution of 10% with 1 module (8% for 2 modules)

Encapsulated Resistive Anode Micromegas

- Benefits from ILC TPC & RD51 developments
- Classical bulk Micromegas + a resistive layer (DLC) allowing charge spreading on neighbouring pads
 - Gives a better spatial resolution with less pads (1728 to 1152) charge/(80ns 0.0012
 - Reduce spark rate
 - Mesh @ ground \rightarrow Better E field homogeneity
- Equipped with water cooling to protect electronic and reduce electronic noise.



Test beams

track 🥆

- All aspects of detector production and performance tested during test beam:
- 2018 @ CERN (*NIM A957 July 2019*)
 → Proof of performance of charge spreading with large pad (70mm2 VS 20mm2 ILC)
- > <u>2019 @ DESY (*NIM A1025 2022*)</u>

→ Procedure, performance with 110mm2 & 400k Ohm/Sq. but not final electronics

› <u>2020 & 2021 @ DESY</u>

 \rightarrow Validation of performances with the final design and electronics

- Now: Production of 32 ERAM detectors
- Track reconstruction takes into account of time and charge seen in neighbouring pad



Charge spreading





ERAM production



- > R&D first tests and validation procedure @ Saclay
 - > During production all moved @ CERN
- > DLC layer is produced in Japan
 - > Able to produce large area with a controlled resistivity ~ 400 kOhm/Sq.
- Detector assembled @ EP/DT PCB workshop CERN
 - > Allows a close following of the production and responsiveness



ERAM tests

Mesh pulsing

- > After delivery the detector is checked with a mesh pulsing
- ➢ Inject signal on the mesh to detect defects affecting outgoing signal: electronic, resistivity, detector geometry
 → Example: ERAM16, amplitude is dominated by electronic response (ASICs)

X-ray scan

- Afterwards detector is scan with 55Fe source: <u>Gain,</u> resolution characterisation
- Automated robot controlled remotely allowing to position source in front of each pad
- Detectors are scanned with their own electronic cards
 - Besides to be a quality control it gives a fine calibration of each ERAM module
- Already 12 detectors fully qualified
 - → Example: ERAM01





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ERAM tests

Difficulties

- During production pads with higher gain & resolution were observed on several detectors:
 - Pads position is correlated with mechanic ribs behind ۶ the detector

Δ.

- Performed fine analysis of X-ray data
 - Can determine interaction position within a pad thanks to charge



thickness after detector assembly.



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Pad non-homogeneity Fixed $R_{i=left,right,top,bottom} = \frac{Q_{lead}^{i} - \mu_{pad}}{\mu_{pad}}$ Pad Y 3750987654547070987 0.1 0.05 0 165 143 121 1 -0.0510 9 8 -0.1 6 5 4

9 101112131415161718192021222324252627282930313233343536 Pad X → Successful correction after change of PCB design, no more non-homogeneity

 $\frac{3}{2}$

2 3 Δ 5 6 7 8 -0.15

Gain and resolution

> We also preformed several measurements of Gain & Resolution at different DLC voltage:



 The dispersion of measurement not proof, requires to correct for environmental conditions (gas composition, pressure & temperature, relative humidity)

Evolution of gain



- > Example: Evolution of the gain as a function of the pressure over temperature
- > We are currently trying to take into account for those variations.

Picture of T2K with the upgrade

- With this upgrade Near detector will improve a lot!
 - Efficiency to reconstruct hadronic contribution
 - Angular acceptance
- T2K will not only benefit of detector upgrade but also of a beam upgrade
 - From 500kW to 750kW and then continuous improvement until >1MW in 2027 for Hyper-Kamiokande

- And in a few years Hyper-Kamiokande will come and ND280 will stay as Near Detector
 - See next talk by Mathieu Guigue!



Conclusion

- T2K has produced high quality results since 10 years and is <u>leading measurement of atmospheric oscillation</u> <u>parameters</u>
 - This performance is possible thanks to a <u>near detector allowing to precisely constrain flux & interaction</u> <u>models</u>
- > With beam upgrade (and Hyper-Kamiokande), systematic uncertainties will become the <u>limitations</u>
- > The ND280 upgrade has been designed to solve present ND280 limitations and be ready for large statistics
 - > The new HA-TPCs allow to reach **larger angular acceptance**
 - > ERAM modules have been characterized thanks to several prototypes and test beam campaigns
 - > Desired performances are reached and ERAM modules are currently in production

Back-up



New PCB design

- Stiffener gluing procedure was first suspect but no clear correlation found after several tests (change of gluing process)
- Assumption that non uniformity of PCB backside affects DLC side flatness and therefore amplification gap by a few microns after pressing DLC
 → PCB modification!
- ERAM up to 16
 - Those areas are also covered with green soldermask
- ERAM09-16
 - PCB produced by ELTOS Cie following industry IPC standard
 - Copper & soldermask is probably thicker than @ CERN
- ERAM17-24
 - Soldermask was removed
- ERAM23
 - Replaced copper pad by a copper mesh
 - → More uniform PCB
 - → More uniform Gain

